TE Internal #: 5145154-8

PCI & PCI Express Connectors, Board-to-Board, 120 Position, .05 in

[1.27 mm] Centerline, Vertical, Natural, Height 13.97 mm [.55 in]





Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: Board-to-Board

Number of Positions: 120

Centerline (Pitch): 1.27 mm [.05 in]

Termination Post & Tail Length: 3.18 mm [.125 in]

Contact Mating Area Plating Material Thickness: [30 µin]

PCB Contact Termination Area Plating Material Thickness

Contact Mating Area Plating Material

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of PCB Mount Retention Features	2
Number of Positions	120
PCB Mount Orientation	Vertical
Ejector	Without
Electrical Characteristics	
Operating Voltage	203 VAC
Body Features	
Product Weight	12.58 g
Bus Width	32 Bit
Contact Features	

2.537 µm

Gold



Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
	30 μin
Contact Current Rating (Max)	1.1 A
Termination Features	
Termination Method to Printed Circuit Board	Through Hole - Solder
Termination Post & Tail Length	3.18 mm[.125 in]
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	1.27 mm[.05 in]
Housing Color	Natural
Dimensions	
Connector Length	84.84 mm[3.34 in]
PCB Thickness (Accepted)	1.57 mm[.062 in]
Connector Height	13.97 mm[.55 in]
Connector Width	8.8 mm[.346 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Bus Type	PCI
Packaging Features	
Packaging Quantity	35
Packaging Method	Box & Carton

Product Compliance

For compliance documentation, visit the product page on TE.com>



EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts







Documents

Product Drawings

STANDARD EDGE .050 SERIES 60 DUAL ASSY

English

CAD Files

Customer View Model

ENG_CVM_CVM_5145154-8_B.2d_dxf.zip

English

3D PDF



3D

Customer View Model

ENG_CVM_CVM_5145154-8_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5145154-8_B.3d_stp.zip

English

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Product Specifications

Application Specification

English